LER Limitations of Thin EUV Resists: Mechanistic Study into Root Causes

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- I. Introduction
- II. PAG Segregation
- **III.** Glass-Transition Temperature
- IV. Summary and Future Directions

Funded by SEMATECH

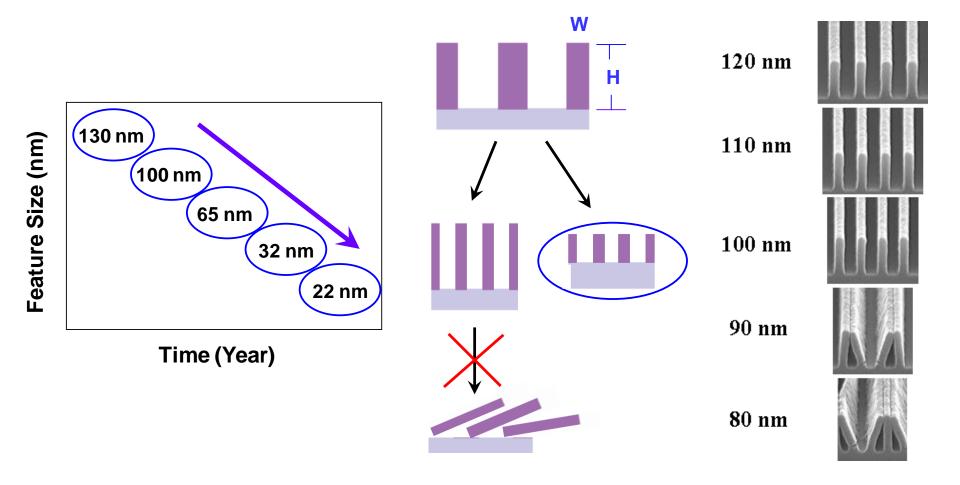


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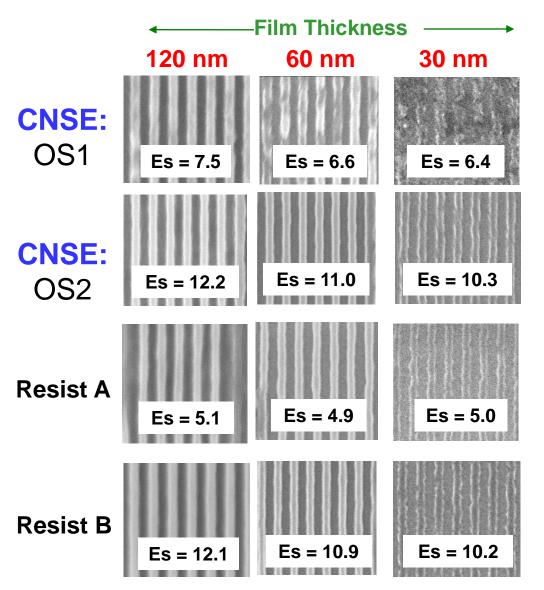
I. Introduction

As Resolution Improves, Resist Thickness must Decrease to Prevent Line Collapse

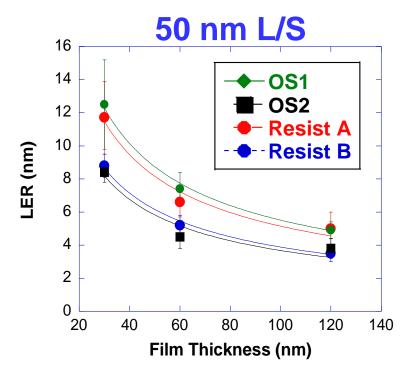


2011 LER Limits of Resist Thin Films:

LER Degrades with Decreasing Film Thickness



Four resists from three sources all show same problem.



Es = Esize (mJ/cm²)

LER Limits of Resist Thin Films

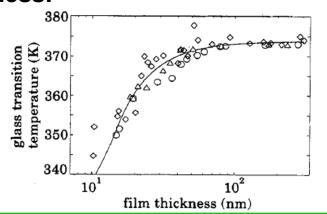
Determine the root cause of the degradation of LER vs. thickness in EUV resists by studying this phenomenon as a function of resist:

- PAG Segregation Today
- Glass Transition Temperature (Tg) Today
- Substrate Interaction SPIE
- Optical Density SPIE

Model for LER vs. Film Thickness

Keddie Model for Tg as a function of film thickness:

$$T_g(d) = T_{g \infty} \left[1 - \left(\frac{A}{d} \right)^{\delta} \right]$$



CNSE Model for LER as a function of film thickness:

$$LER(d) = LER_{\infty} \left[1 + \left(\frac{A'}{d} \right)^{\delta'} \right]$$

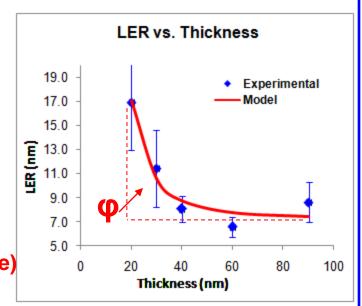
 $T_{\alpha}(\infty) = Bulk Tg$

A' = Thickness Dependence

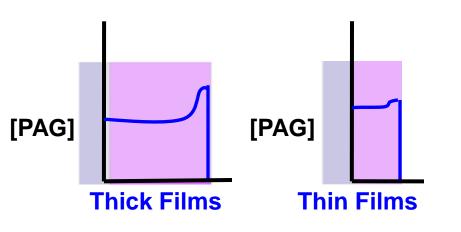
δ' = Exponential

 ϕ = Area under LER curve

(Larger $\phi \rightarrow$ Worse LER thickness dependence)

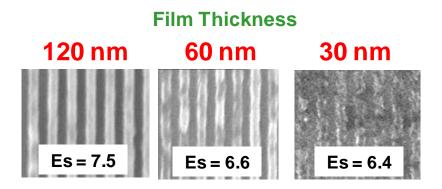


II. PAG Segregation



Fluorinated PAGs are know to segregate to resist surfaces.

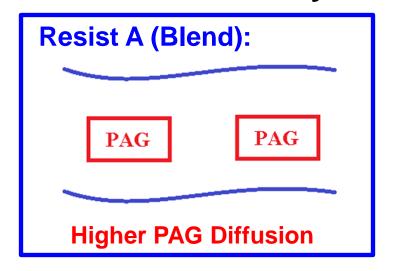
This stratification can cause surface inhibition, and flatter resist tops. (Less top-loss)

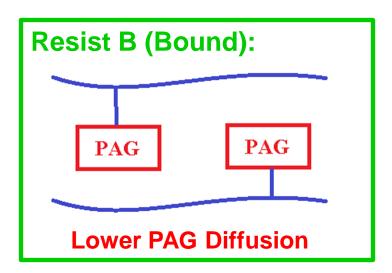


Could changes in the concentration of PAG at the surface be responsible for poorer imaging in thin films?

Exploration of Three JSR Resists:

Resists Provided by JSR:



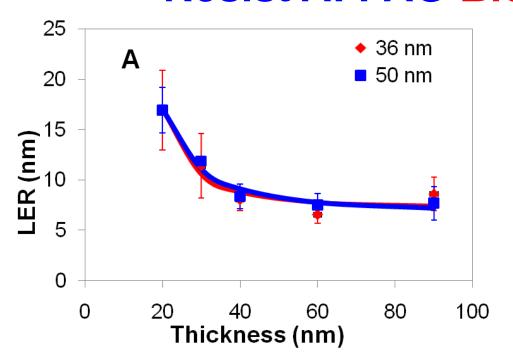


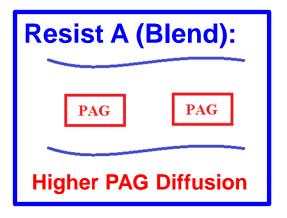
Resists A and B have a comparable polymer.

Resist C (Blend):

Baseline Litho

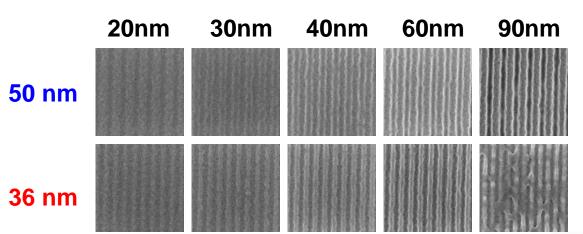
Resist A: PAG Blend Resist





CNSE Model:

$$LER(d) = LER_{\infty} \left[1 + \left(\frac{A'}{d} \right)^{\delta'} \right]$$



Avg φ: 128 nm²

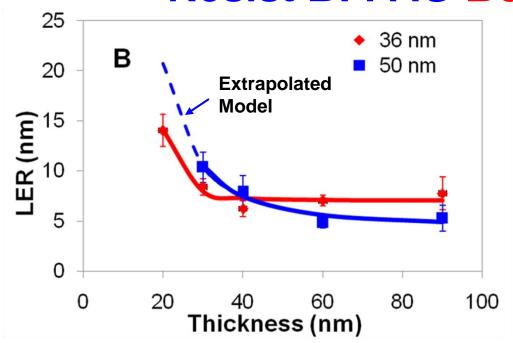
$$\phi_{50} = 149 \text{ nm}^2$$

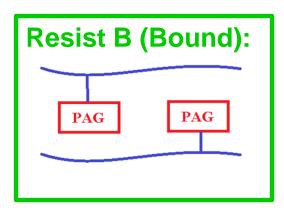
$$\phi_{36} = 107 \text{ nm}^2$$

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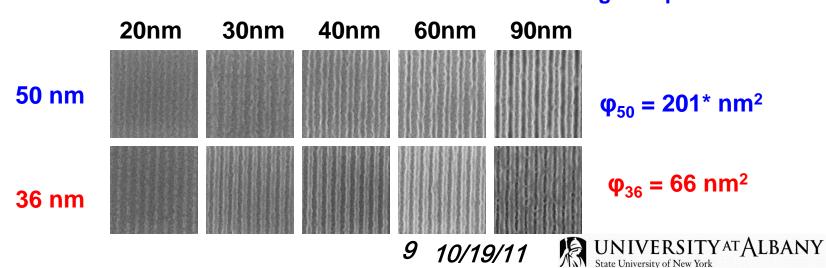
Resist B: PAG Bound Resist



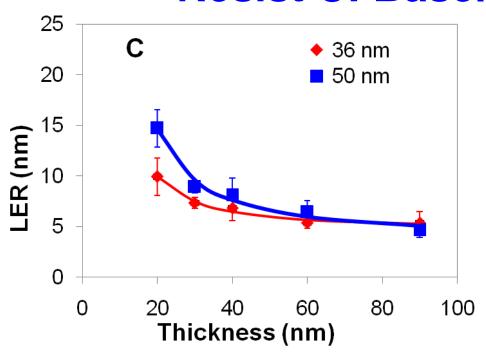


Avg φ: 134 nm²

* 50 nm h/p data at 20 nm thickness was not resolved. Model is fit off of the remaining four points.



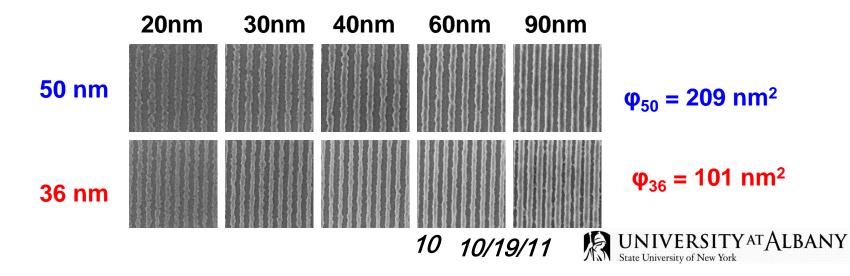
Resist C: Baseline Resist



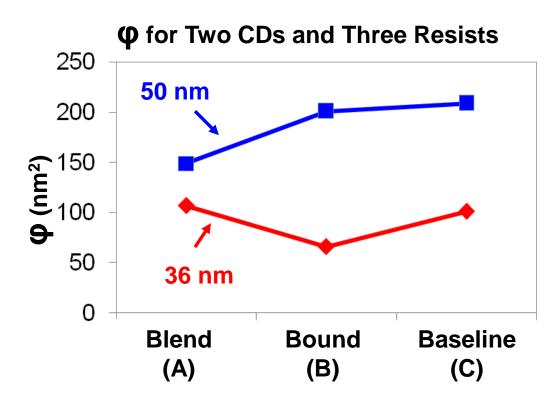
Resist C (Blend):

Baseline Litho

Avg φ: 155 nm²

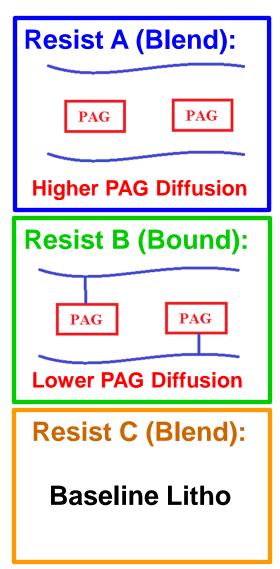


Exploration of Three JSR Resists:



Higher φ: Worse LER thickness dependence.

Bound PAGs have better ϕ for 36-nm lines and worse ϕ for 50-nm lines.

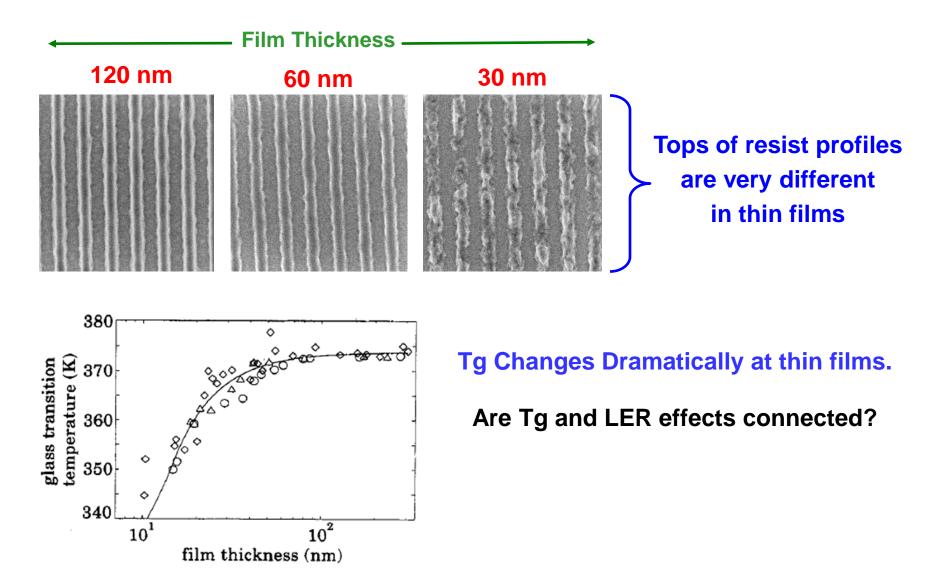


LER Limits of Resist Thin Films

Determine the root cause of the degradation of LER vs. thickness in EUV resists by studying this phenomenon as a function of resist:

- PAG Segregation Today
- Glass Transition Temperature (Tg) Today
- Substrate Interaction SPIE
- Optical Density SPIE

III. Glass-Transition Temperature



Systematic Study of Polymer Tg on LER/Thickness Problem

Prepare high & low Tg polymers and determine:

LER vs. thickness.

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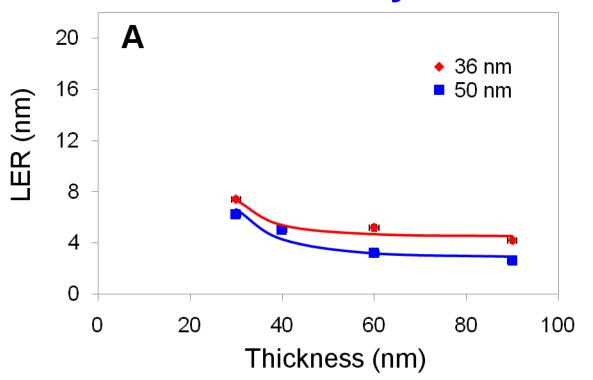
[101°C]

65

Acid-diffusion length (EL) vs. thickness

^{*} Tg values in brackets are modeled results. Bicerano, "Prediction of polymer properties" / Fox Tg

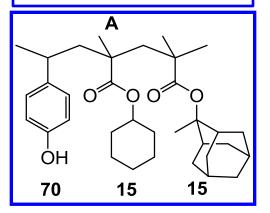
Polymer A



PAB: 130 °C / 60 s

PEB: 110 °C / 90 s

 $T_{g \infty} = 162 \text{ }^{\circ}\text{C}$



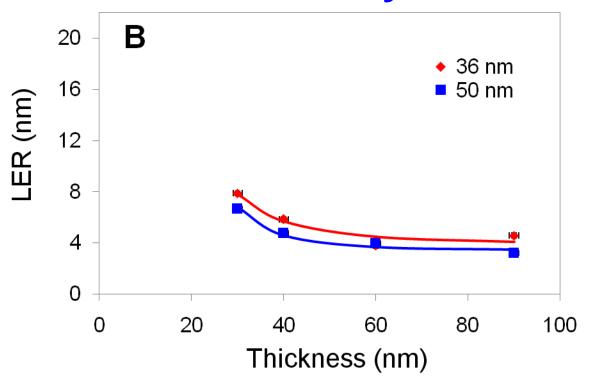
$$\phi_{50} = 46 \text{ nm}^2$$

$$\phi_{36} = 27 \text{ nm}^2$$

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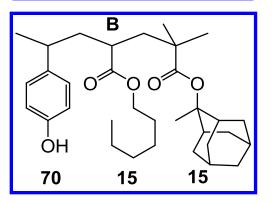
Polymer B

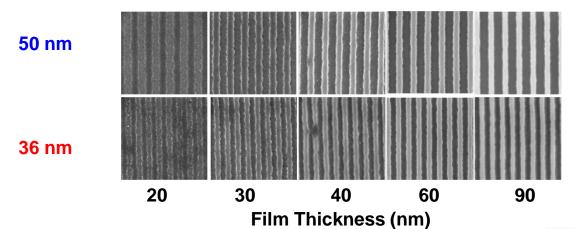


PAB: 130 °C / 60 s

PEB: 110 °C / 90 s

 $T_{g oo} = 157 \, {}^{\circ}\text{C}$





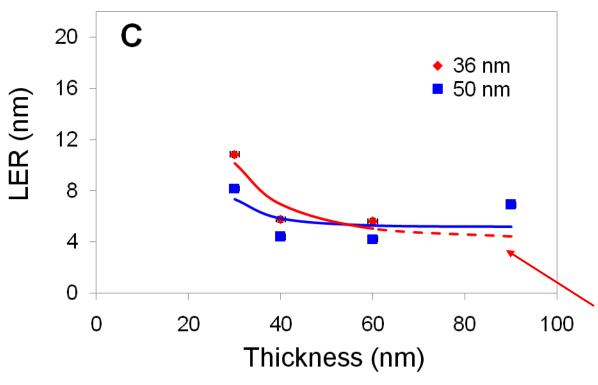
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$$\phi_{50} = 36 \text{ nm}^2$$

$$\phi_{36} = 59 \text{ nm}^2$$

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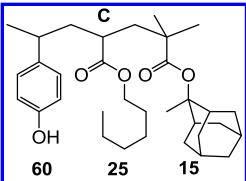
Polymer C



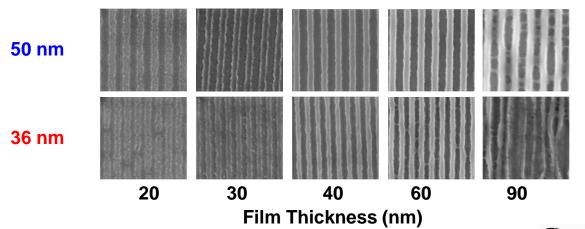
PAB: 130 °C / 60 s

PEB: 110 °C / 90 s

 $T_{g oo} = 130 \, {}^{\circ}\text{C}$



Extrapolated Model

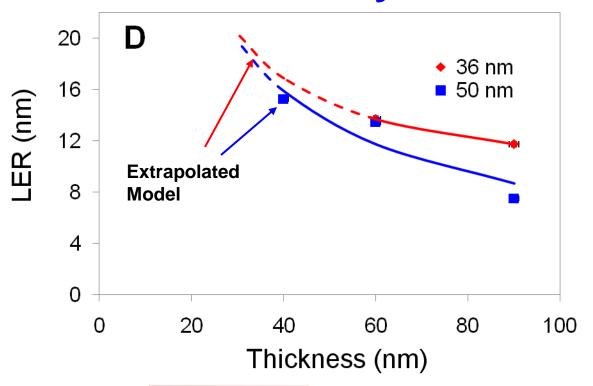


$$\phi_{50} = 20 \text{ nm}^2$$

$$\phi_{36} = 93 \text{ nm}^2$$

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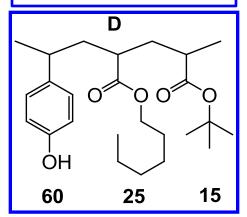
Polymer D

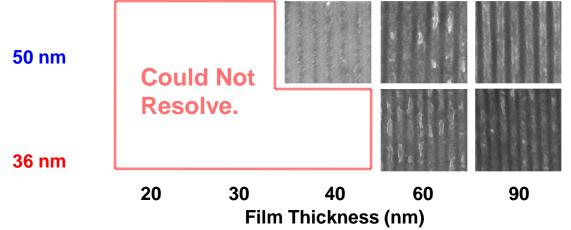


PAB: 130 °C / 60 s

PEB: 110 °C / 90 s

 $T_{g oo} = 106 \, {}^{\circ}\text{C}$





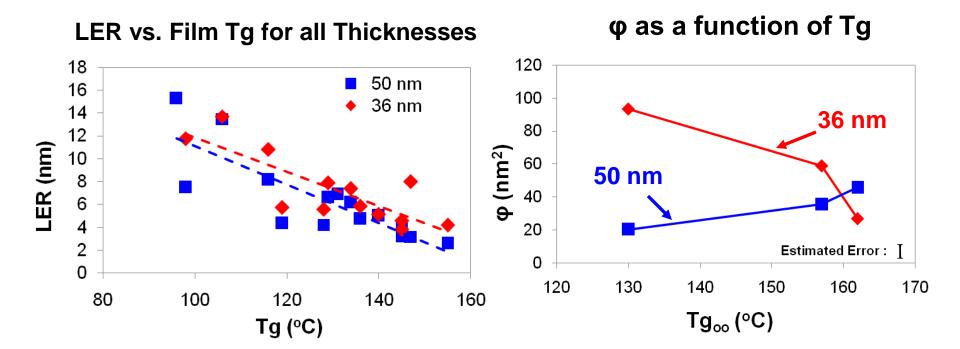
 $\phi_{50} = 743 \text{ nm}^2$

 $\phi_{36} = 349 \text{ nm}^2$

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Comparison of Tg Results



- In general, LER gets worse at higher Tg.
- Since Tg is a function of thickness, this may partially explain LER degradation.
- As Tg in increases, the ϕ for 36-nm lines improves while the ϕ for 50 nm lines gets worse.

Summary and Future Directions

PAG Segregation:

- A mathematical model was developed to quantify the dependence of film thickness on LER (φ).
- This model was applied to three JSR resists; two of which directly compare PAG mobility in a film.
- In particular, φ, is better for small CDs (36 nm half-pitch).

Glass Transition Temperature:

- A series of polymers were designed with similar lithographic properties but varying glass transition temperatures.
- Here, φ improves with increasing Tg for 36-nm lines, but gets worse for 50-nm lines.
- These results point towards a possible acid diffusion mechanism. More investigation is needed.

Optical Density and Substrate Interaction:

 We are currently evaluating the effect of optical density and substrate interaction on LER through film thickness.

Acknowledgements

Group Members Past and Present:

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Staff at EMET

Staff at BMET

King Industries

Dow Chemical

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Ellipsometry Help:

Alain Diebold

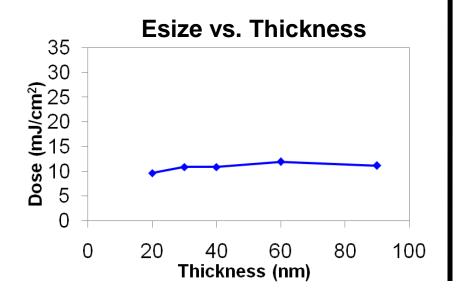
And you for your time...

Appendix

Resists Coated to 20-nm Showed Unusual Behavior on Silicon

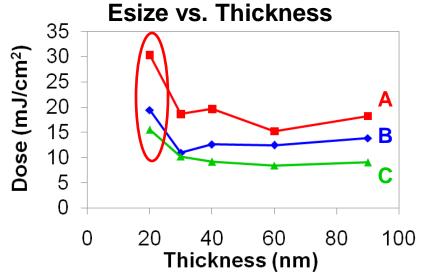
PAG Segregation:

- Albany EMET
- NCX011 Underlayer
- JSR Resists



Glass Transition Temperature:

- Berkeley BMET
- Primed Silicon
- CNSE Resists

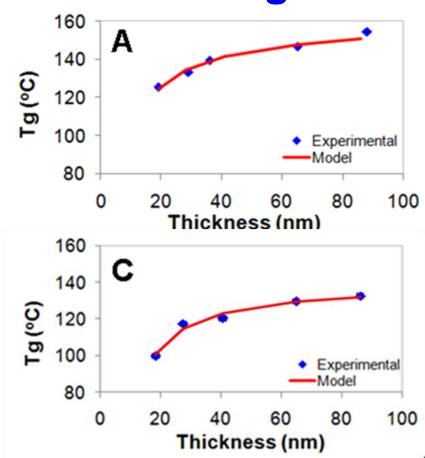


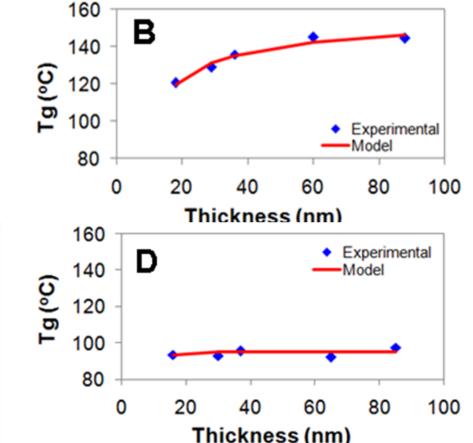
These 20-nm results were omitted from the Tg study.

Further investigation into this peculiarity is planned.



Tg vs. Film Thickness



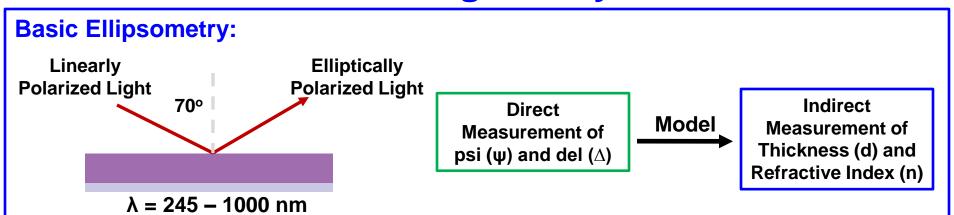


Keddie Equation:¹

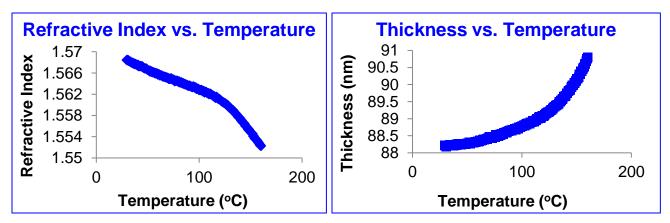
$$T_g(d) = T_{g \infty} \left[1 - \left(\frac{A}{d} \right)^{\delta} \right]$$

<u> </u>		
Polymer	Tg oo	φ _{Tg} (nm ⋅ °C)
Α	162	1266
В	157	1235
С	130	884
D	106	528

Measurement of Tg in Polymer Films



Glass Transition (Tg): Temperature at which a polymer can overcome cohesive energy.



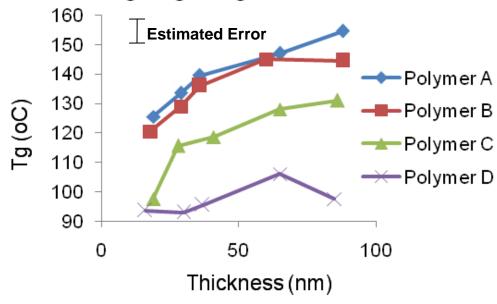
$$h(T) = w\left(\frac{M-G}{2}\right) ln\left[cosh\left(\frac{T-T_g}{w}\right)\right] + \left(T-T_g\right)\left(\frac{M+G}{2}\right) + c^{(1)}$$

Films were heated from 25 to 160 °C for 20 mins to outgas residual solvent. Measurements were then taken on cooling from 160 to 25 °C for 20 mins and data fitted to Dalnoki-Veress eq.



Polymer Set Design for Initial Exposure Studies

Avgeraged Tg vs. Thickness

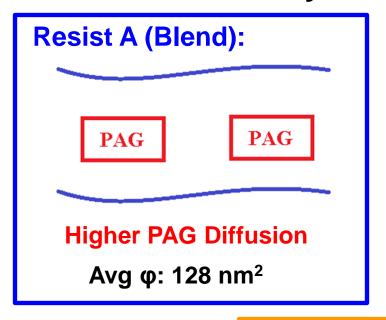


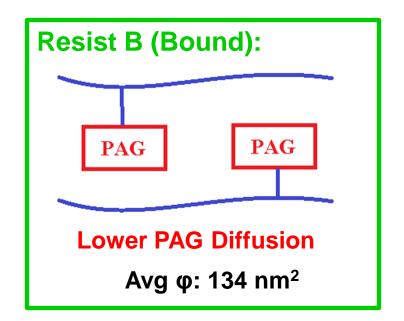
^{*} Tg values averaged between thickness and refractive index curves



PAG Segregation Summary

Resists Provided by JSR:





Resist C (Blend):

Baseline Litho

Avg φ: 155 nm²

Brian: Not Ave.

The resists tested seem to have different results depending on CD.

